TPSM5D1806RDBR

Quality, reliability & packaging data download

Status: ACTIVE

Report date: 03/06/2026

Assembly site: **Ext-Mfg**

RoHS	Exempt
REACH	Yes
Device marking	TPSM5D1806
Lead finish/Ball material	NiPdAu
MSL rating/Peak reflow	Level-3-260C-168 HR
Rating	Catalog

Material content

Due to complexity of a material content report for modules and EVMs, a detailed report is not displayed on-line. Please download the spreadsheet or XML data for this information here: Material content search results

MTBF/FIT estimates

MTBF / FIT		**MTBF / FIT supporting data**							
MTBF	**FIT**	**Usage temp (°C)**	**Conf level (%)**	**Activation energy (eV)**	**Test temp (°C)**	**Test duration (hours)**	**Sample size**	**Fails**	**Additional comments**
8.71×10^9	0.1	55	60	0.7	125	1000	101758	0	—

Qualification summary

Stress	Reference	Min lot qty	SS / lot	Condition	Duration	Result	Notes
HTOL	JESD22-A108	3	77	Life test, 125C	1000 hours	Pass	Or equivalent JEDEC condition
HTSL	JESD22-A103	3	25	High temp storage bake, 150C	1000 hours	Pass	Or equivalent JEDEC condition
AC/UHAST	JESD22-A102/JESD22-A118	3	25	Unbiased HAST 130C / 85% RH	96 hours	Pass	Or equivalent JEDEC condition
THB/HAST	JESD22-A101/JESD22-A110	3	25	HAST 130C/85%RH	96 hours	Pass	Or equivalent JEDEC condition
TC	JESD22-A104	3	25	Temperature cycle -65/150C	500 cycles	Pass	Or equivalent JEDEC condition
SD	J-STD-002	3	22	Per specification	>95% lead coverage	Pass	—
HBM	JS-001	1	3	ESD - HBM	Classification	See data sheet	—
CDM	JS-002	1	3	ESD - CDM	Classification	See data sheet	—
LU	JESD78	1	3	Latch-up	Per JESD78	Pass	As applicable per JESD78
MSL	J-STD-020	—	—	Per J-STD-020	Classification	See data sheet	—

Ongoing reliability monitoring

FAB process reliability data

Fab Process	Reliability Test	Rolling Year (1Q2025 - 4Q2025) Sample Size	Cumulative Sample Size	Disposition
Power BICMOS	High temperature reverse bias 125C, 1000 Hours or Equivalent JEDEC Condition	231	462	Pass
Power BICMOS	Life test 125C, 1000 Hours or Equivalent JEDEC Condition	28045	439346	Pass

Assembly process reliability data

Package Family	Reliability Test	Rolling Year (1Q2025 - 4Q2025) Sample Size	Cumulative Sample Size	Disposition
QFN	Biased HAST 130C/85%RH, 96 Hours or Equivalent JEDEC Condition	13564	167937	Pass
QFN	High temp storage bake 150C, 1000 Hours or Equivalent JEDEC Condition	13977	158878	Pass
QFN	Temperature cycle -65/150C, 500 Hours or Equivalent JEDEC Condition	39039	409462	Pass
QFN	Unbiased HAST 130C/85% RH, 96 Hours or Equivalent JEDEC Condition	22602	296180	Pass

Additional resources

General quality guidelines

Certifications

Conflict minerals specialized disclosure report

Restricted chemical test report

For additional component information, please visit Material content search

For additional information, please contact TI customer support center

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